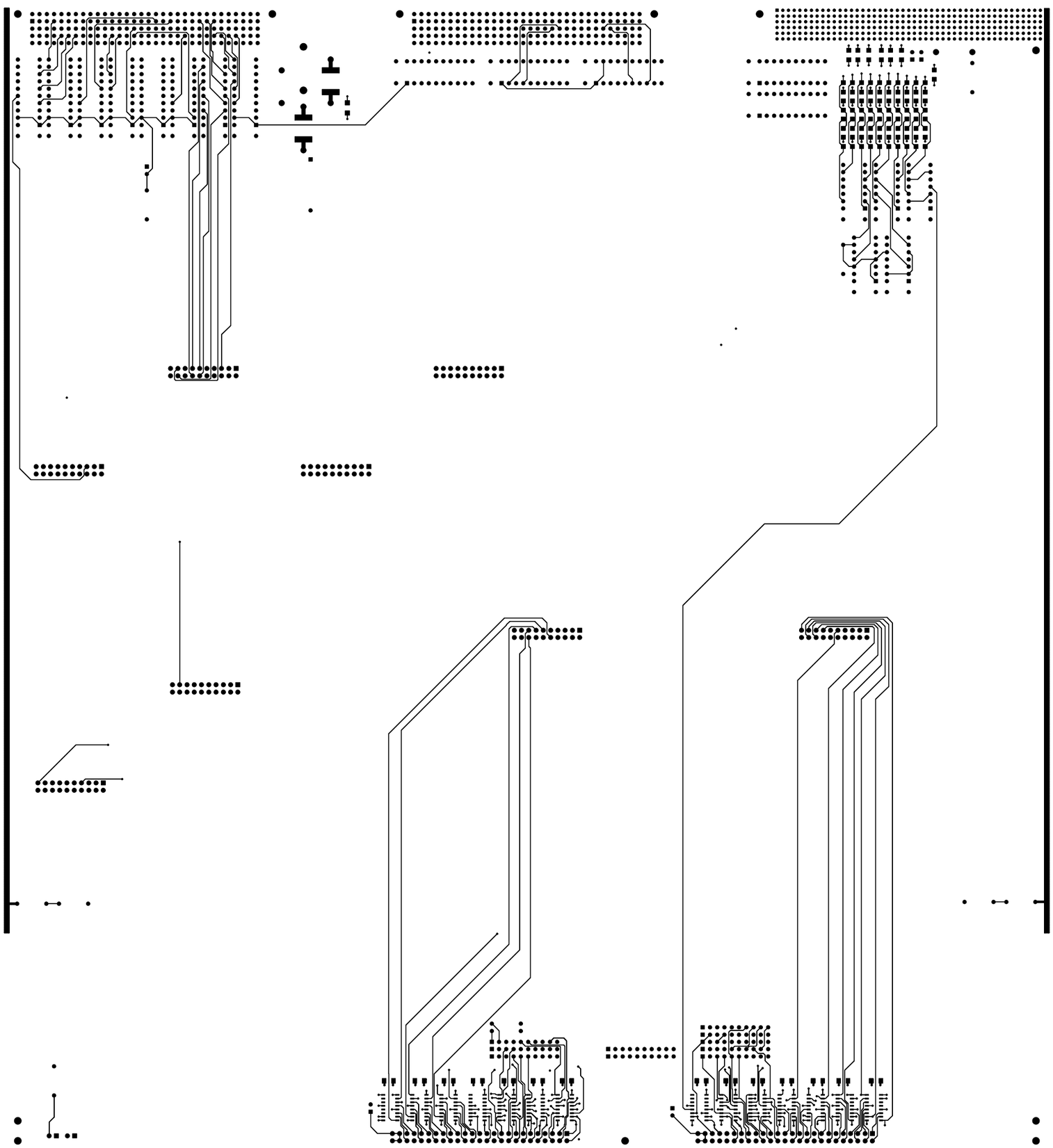
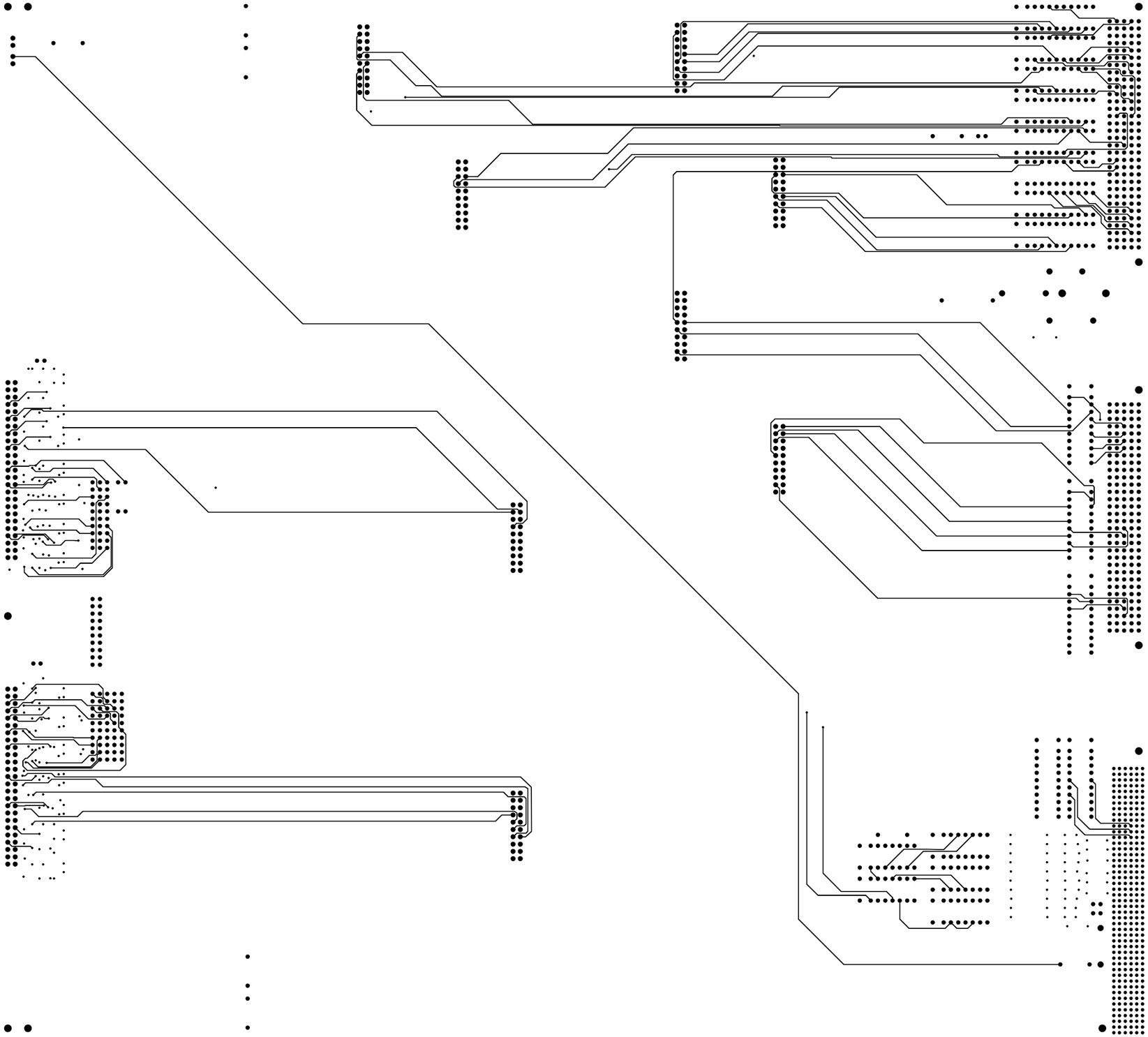
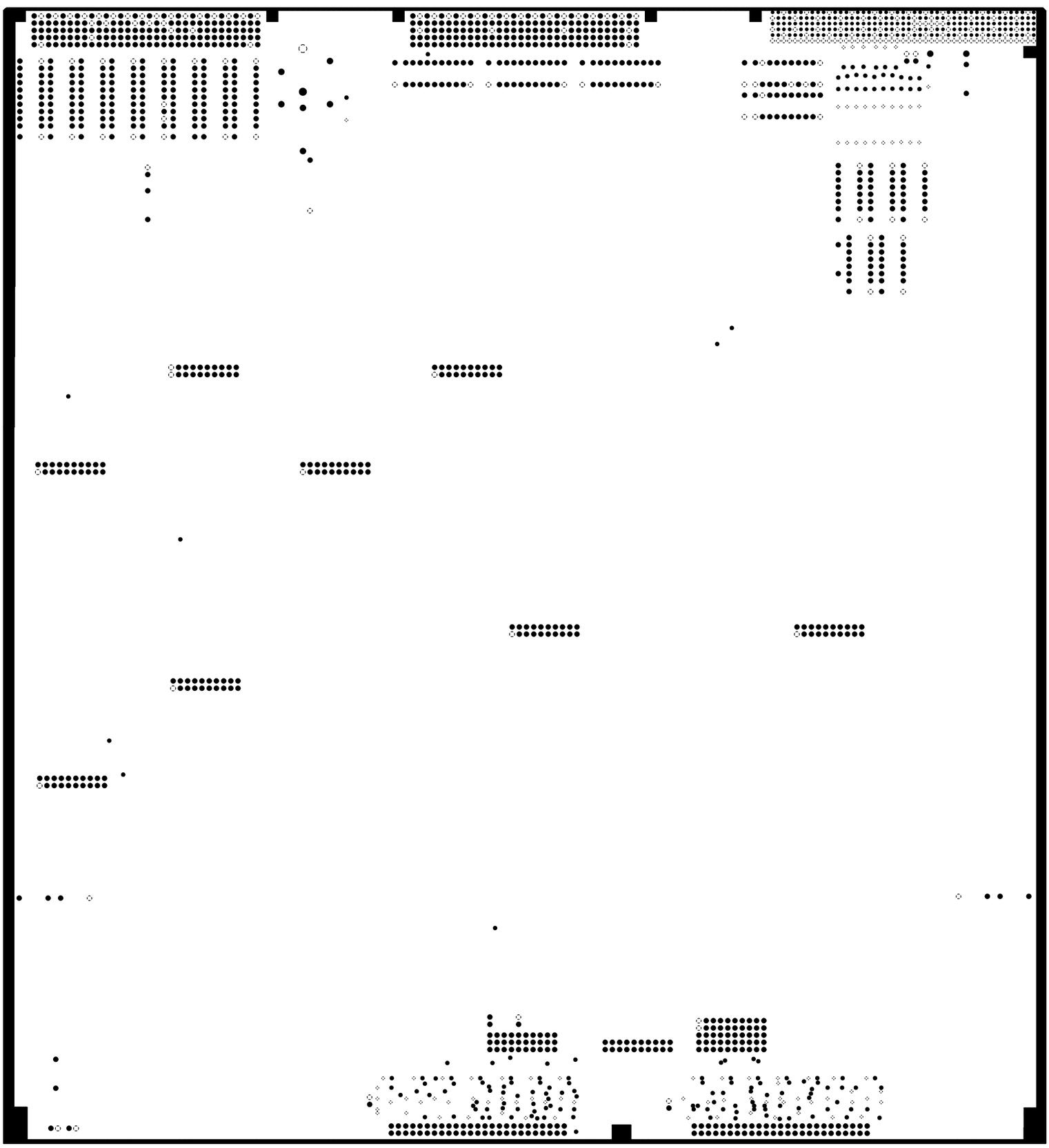
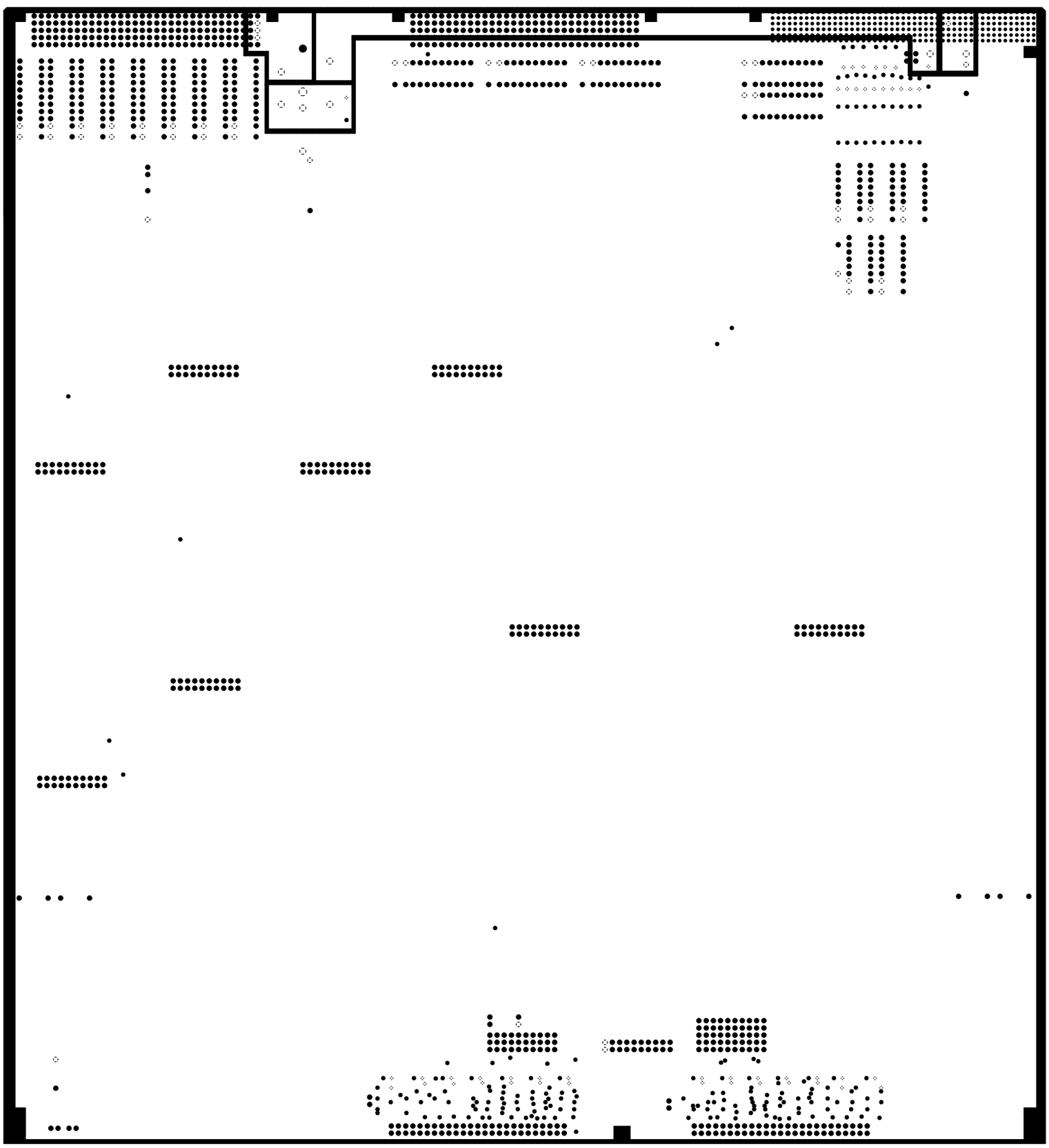
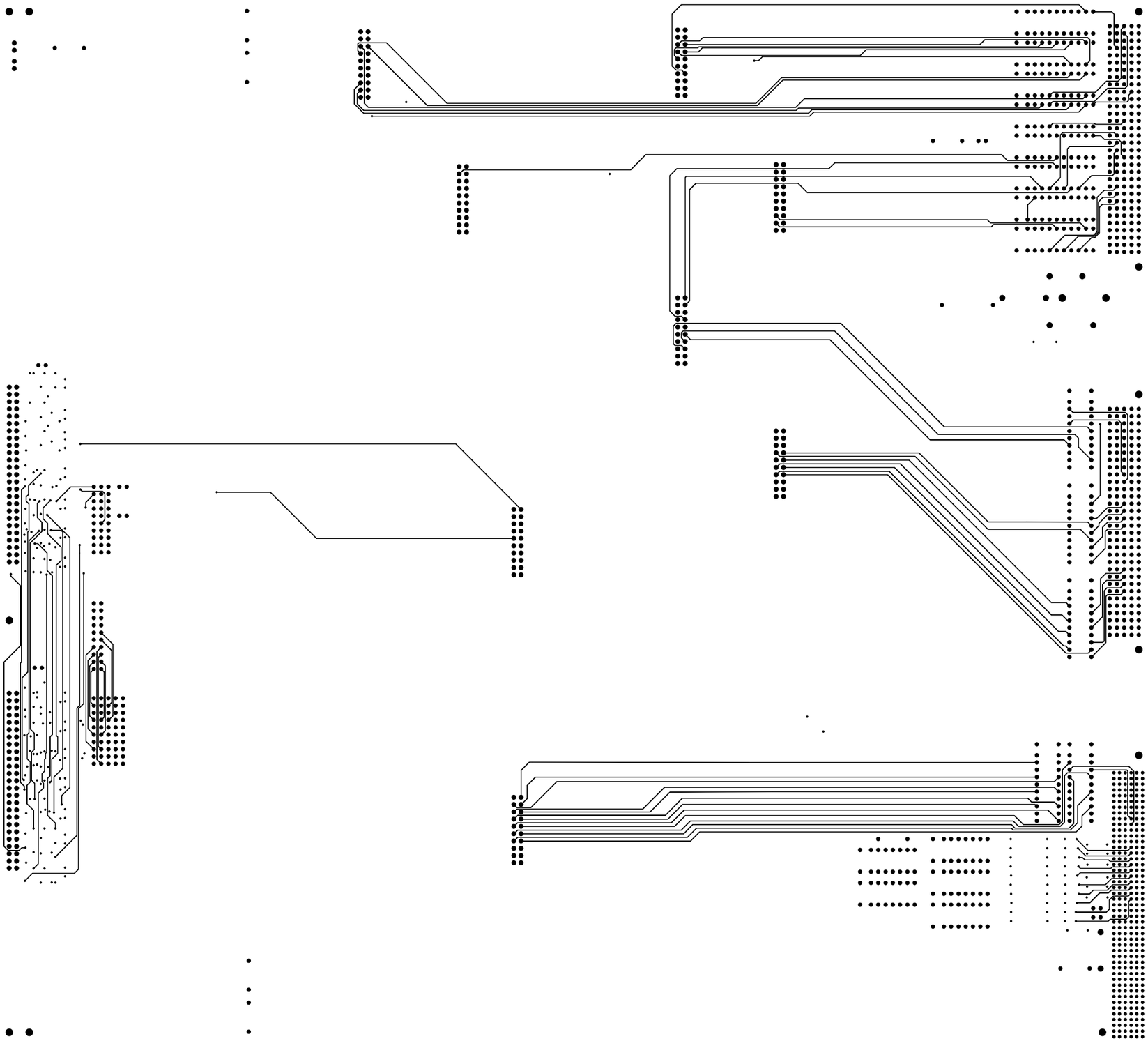
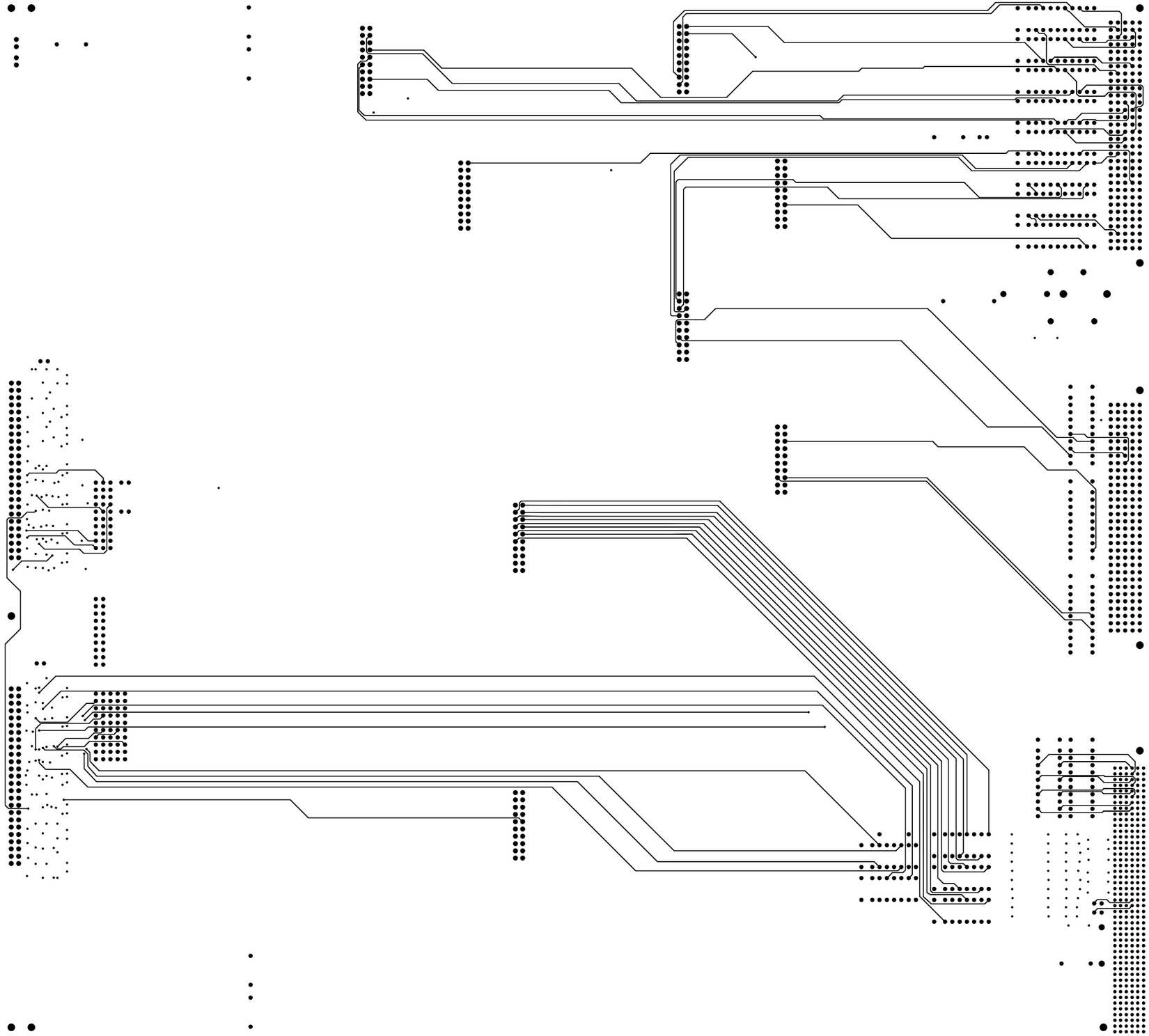


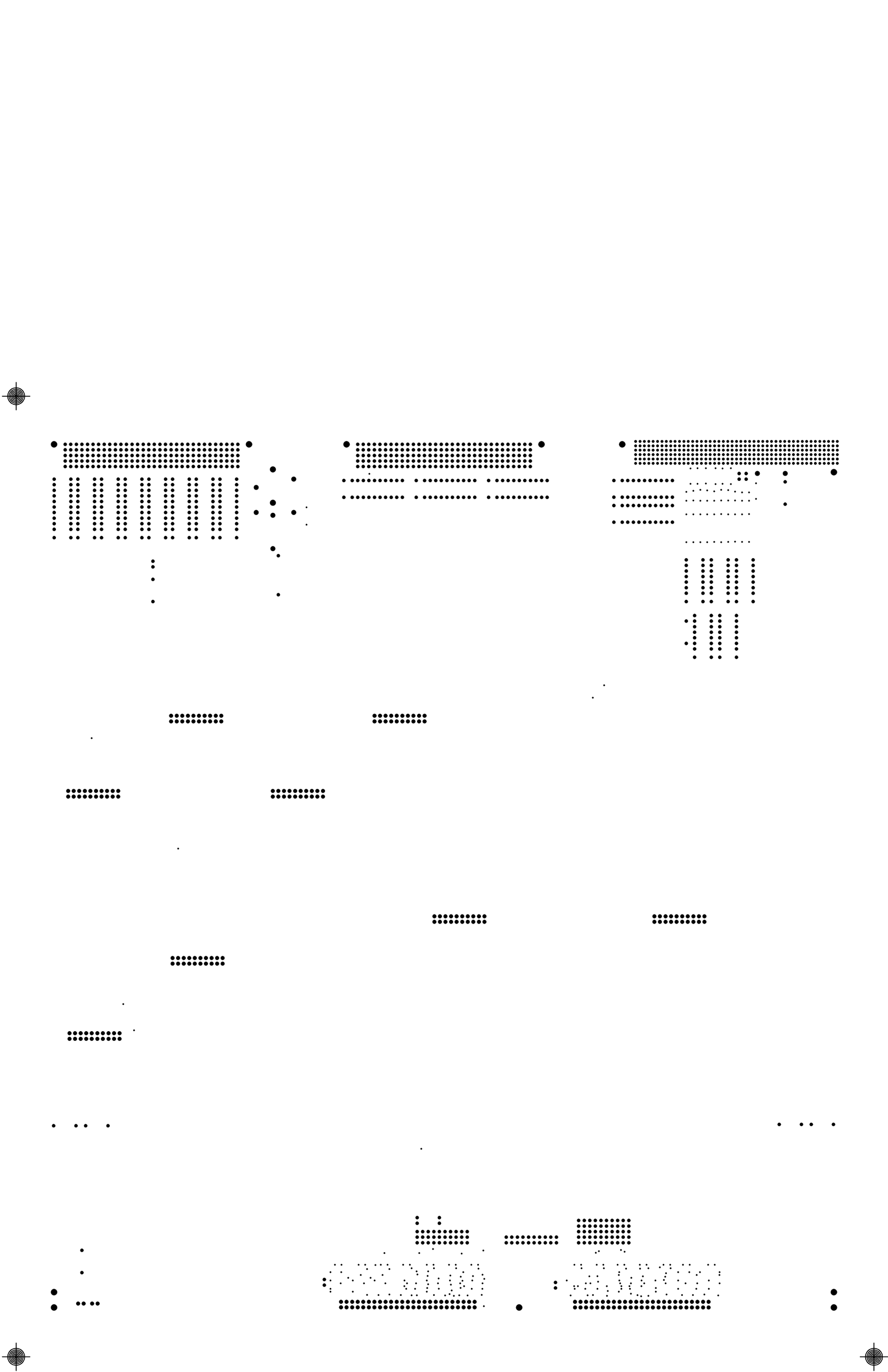


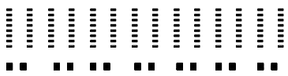


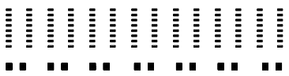


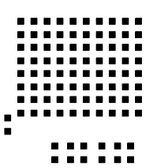


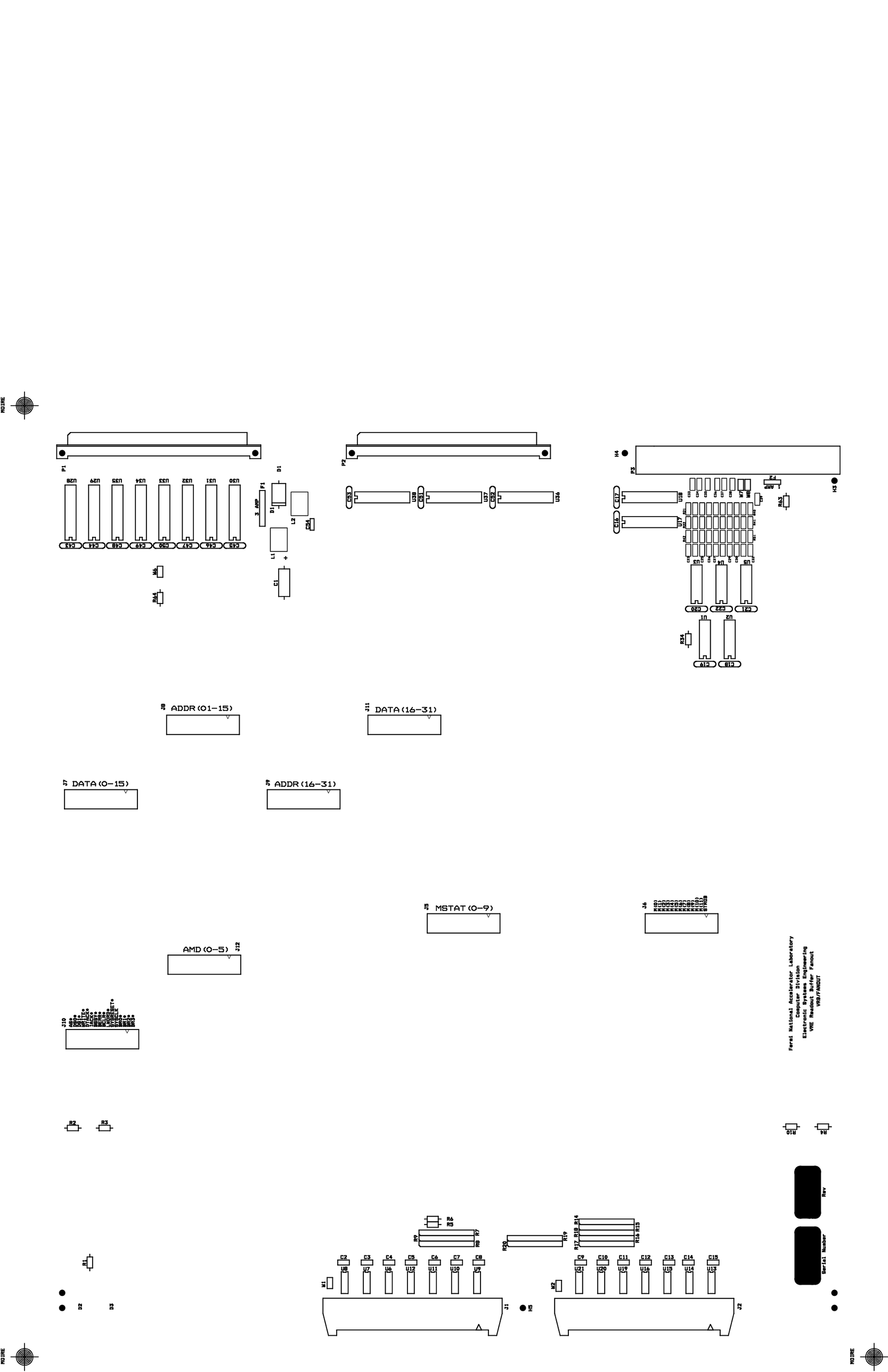


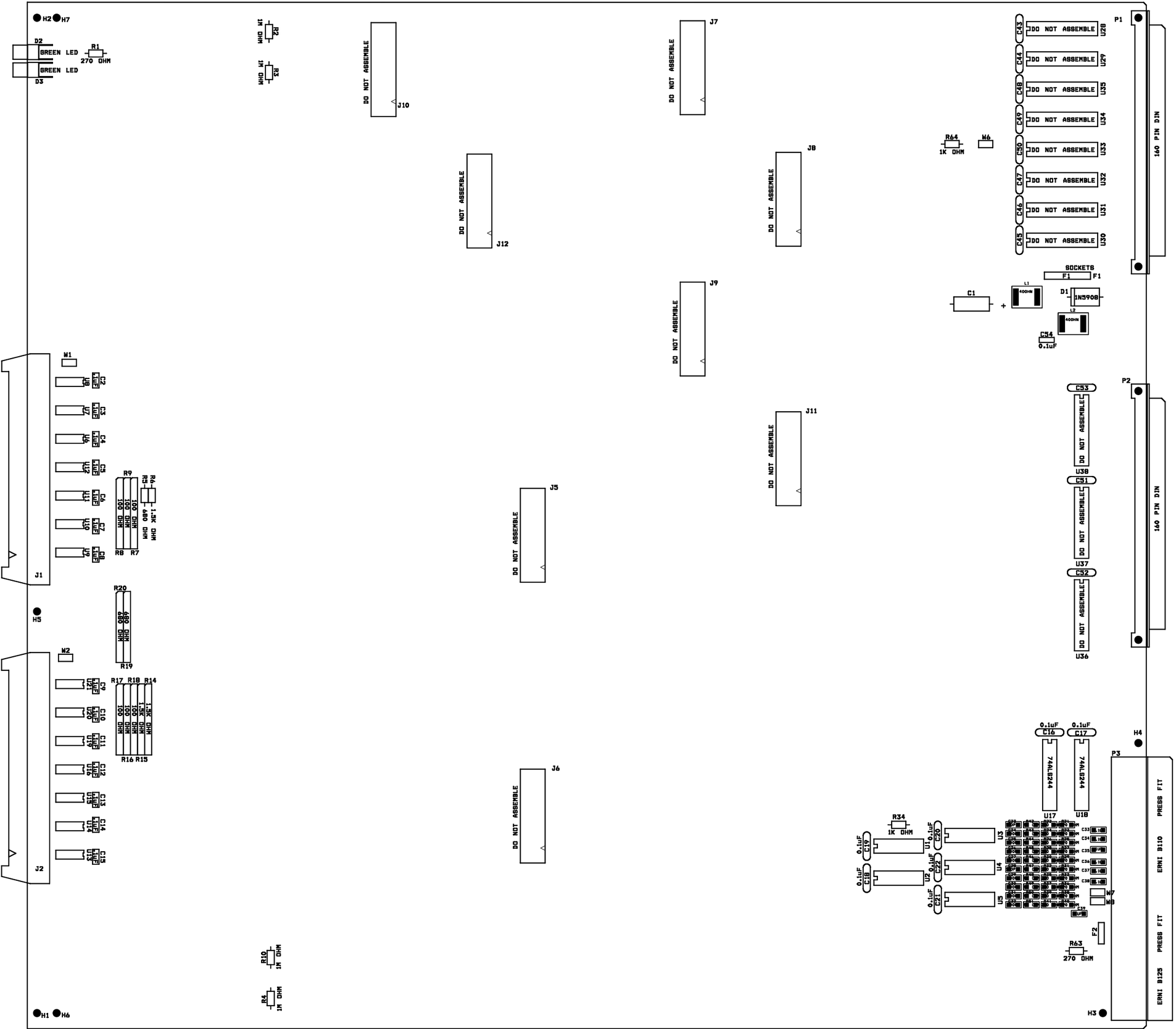






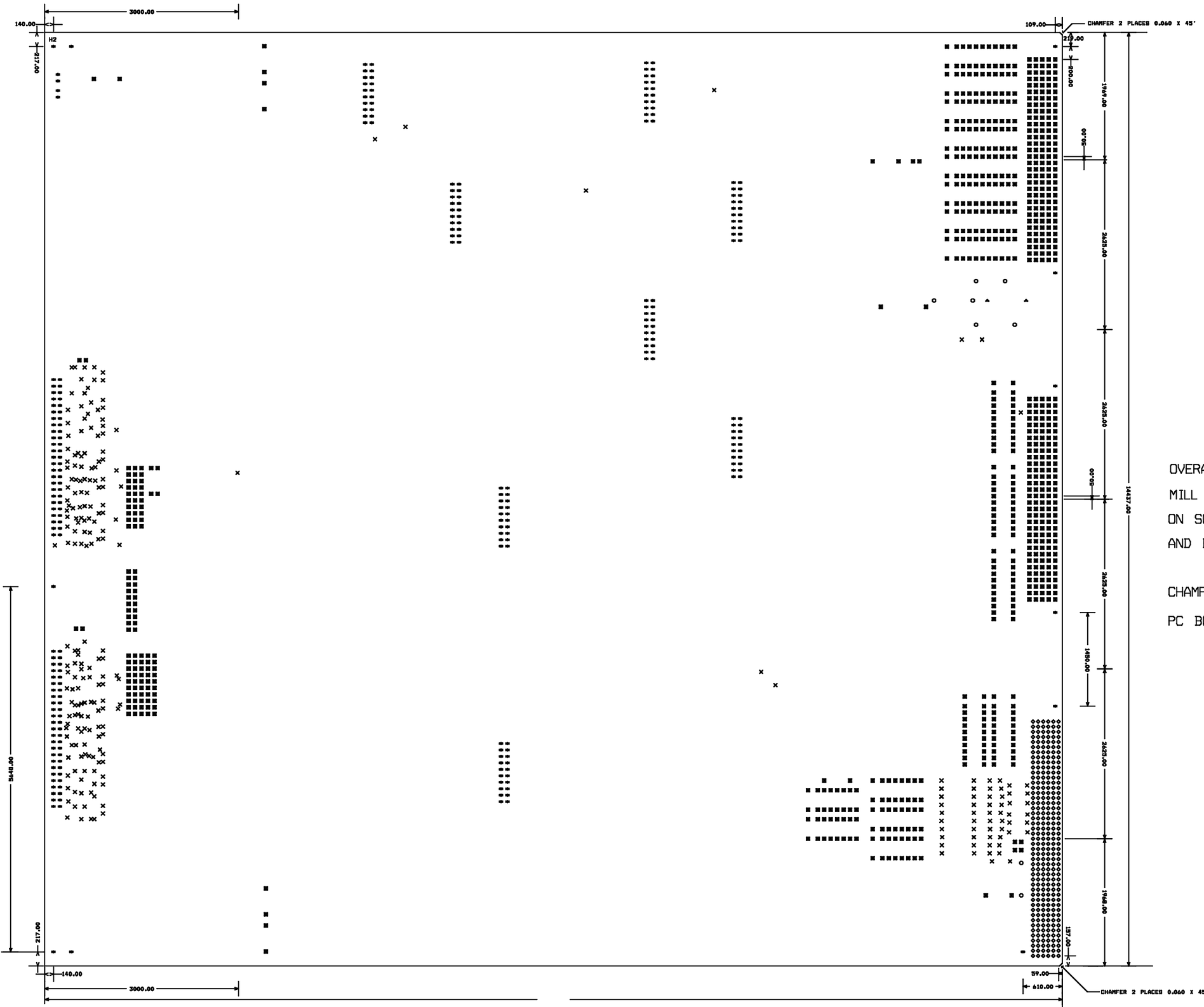



P1
P2
P3
H4
H5
D1
F1
3 AMP
L2
L1
C1
J8 ADDR(01-15)
J11 DATA(16-31)
J7 DATA(0-15)
J9 ADDR(16-31)
J3 MSTAT(0-9)
J4
AMD(0-5) J12
J10
J1
J2
M1
M2
R2
R3
R4
R10
Fermi National Accelerator Laboratory
Computer Division
Electronic Systems Engineering
VME Readout Buffer Fanout
VRBF/ANOUT
Rev
Serial Number



DO NOT ASSEMBLE THESE COMPONENTS,
THESE THRU HOLES SHOULD BE MASKED OFF,
THEY WILL BE ASSEMBLE LATER IF NECESSARY.

C43	J5	U28	W1	R64
C44	J6	U29	W2	
C45	J7	U30	W6	
C46	J8	U31	W7	
C47	J9	U32	W8	
C48	J10	U33		
C49	J11	U34		
C50	J12	U35		
C51		U36		
C52		U37		
C53		U38		



DRILL CHART				
SYM	DIAM	TOL	QTY	NOTE
×	0.012		240	
◇	0.025		282	
■	0.034		818	
*	0.038		264	
o	0.055		8	
▲	0.080		2	
⊕	0.110		11	NOT PLATED
TOTAL			1625	

BOARD LAYER STACKING ORDER

TOP LAYER 1 = TOP LAYER

INNER LAYER 2 = INNER TRACE 1

INNER LAYER 3 = GROUND PLANE

INNER LAYER 4 = POWER PLANE

INNER LAYER 5 = INNER TRACE 2

BOTTOM LAYER 6 = BOTTOM LAYER

OVERALL PC BOARD THICKNESS = 0.093 +/- 0.008 INCH

MILL PC BOARD EDGE TO A THICKNESS OF 0.063 +/- 0.008 INCH ON SOLDER SIDE FOR A DISTANCE OF 0.098 INCH FROM THE TOP AND BOTTOM OF THE BOARD.

CHAMFER FRONT 2 CORNERS OF BOARD 0.060 X 45 DEGREES

PC BOARD DIMENTIONS ARE IN MILS